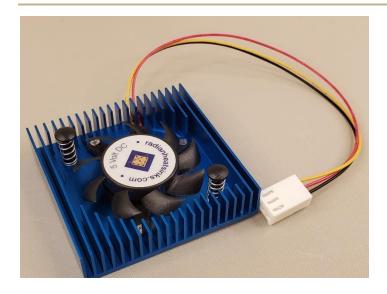
# Sub-Zero PCle Fansink – SZ05S

Radian Thermal Products has been committed to helping our customers with full-service mechanical and thermal solutions since 1974. Radian offers a range of standard PCIe active and passive cooling solutions as well as custom designs to meet customer requirements.



# **Description:**

Bυ

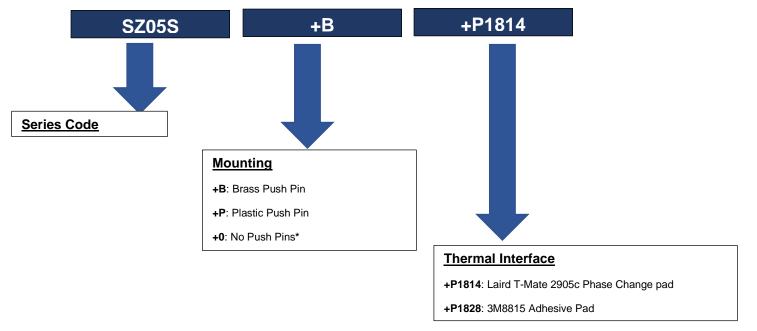
Ra

 Sub-Zero PCIe Fansink, 50 x 50 x 10.5mm, 5V

iy Online at:		
adianheatsinks.com		
PART	SZ05S	
MOUNTING	Push Pin	
MATERIAL	Aluminum	
LENGTH (mm)	50.0	
WIDTH (mm)	50.0	
HEIGHT (mm)	10.5	
VOLTAGE (V DC)	5.0	

## **Model Numbering System**

Part numbers can be customized as follows:



\*Must be combined with 3M8815 Adhesive Pad.



# **Fansink Specifications**

Thermal Data		
θ <sub>sA</sub> <sup>1</sup> (°c/w)	2.2	
	3M 8815 Adhesive Pad	
TIM Options	LAIRD T-MATE 2905c	
	Contact Radian for other options	

Mechanical Data		
Assembly Dimensions	See Figure 1	
Heatsink Material	Aluminum	
Surface Finish	Radian Blue Anodized	
Force per Push Pin (Ib <sub>f</sub> )	Brass: 1.6 ±15% Maximum	
	Plastic: 1.6 ±15% Maximum	
Push Pin Effective Length (mm) (See Figure 2)	Brass: 13.72 ±0.127	
	Plastic: 12.29 ±0.127	
Maximum Combined Thickness (mm) <sup>2</sup>	Brass: 11	
	Plastic: 9.5	
Push Pin Extension Length under PCB (mm) (See Figure 2)	Brass: 2.16 ±0.127	
	Plastic: 3.2 ±0.127	
Recommended PCB Hole Diameter for Push Pin (mm)	Brass: 3.0	
	Plastic: 3.2	
Connector	Molex 22-01-3037	
Connector Receptacle	Mates KK 254 PCB Headers	
Mass (g)	23	
Noise (dB)	33.85	

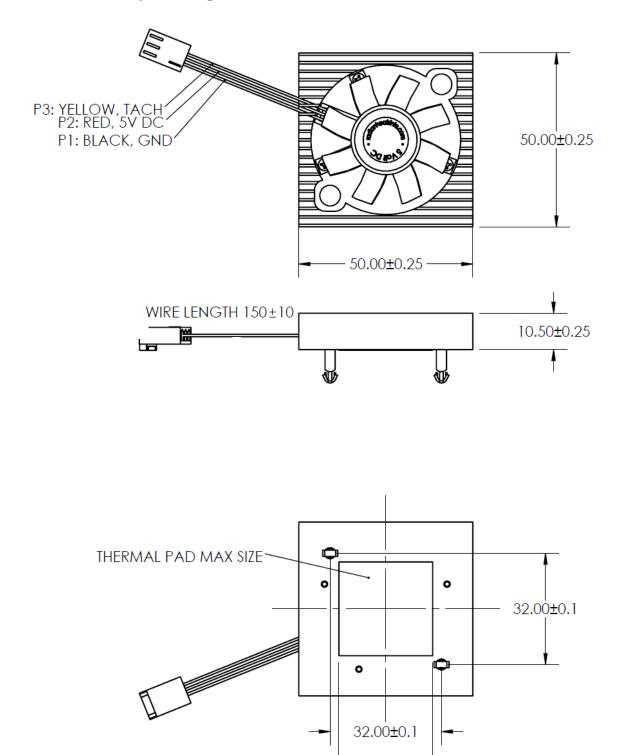
Electrical Data		
Operating Voltage ( $V_{DC}$ )	5	
	6.2 Max	
Connector Pins	08-50-0114 OR EQUIVALENT	
Starting Voltage (VDC)	4 (ON/OFF)	
Input Current (A)	0.19 +/- 0.02	
Wire Description	See Figure 1	
Signal Circuit	See Figure 3	

Environmental Data		
Operating Temperature (°C)	-10 to +70	
Storage Temperature (°C)	-40 to +75	
Operating Humidity (%RH)	5 to 90	
Storage Humidity (%RH)	5 to 95	
MTBF	30,000 hours continuous operation at 25°C with 15~65 %RH.	

<sup>&</sup>lt;sup>1</sup> Typical value, actual performance may vary depending on application environment. <sup>2</sup> Combined thickness is the sum of the PCB, chip, thermal pad and heatsink base thicknesses.



#### **Fansink Assembly Drawings**



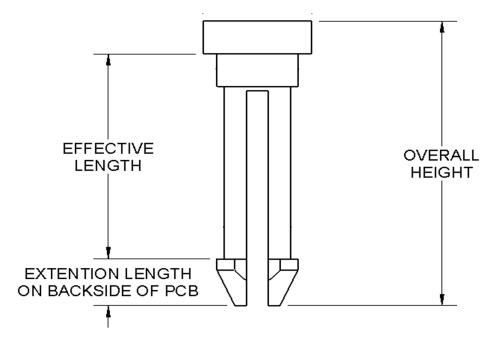
**DIMENSIONS IN mm** 



□27.0±0.5



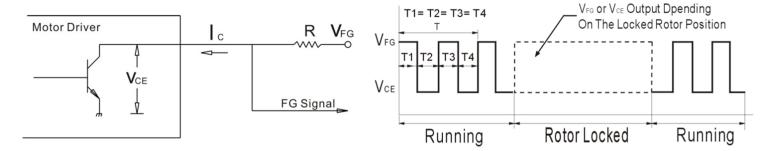
### **Push Pin Illustration**





## **Fan Circuit Schematic**

Output Waveform



#### Figure 3: SZ05S Signal Circuit Schematic